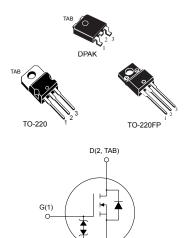


Datasheet

N-channel 400 V, 0.85 Ω typ., 5.4 A, SuperMESH[™] Power MOSFETs in DPAK, TO-220 and TO-220FP packages



S(3)

Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STD7NK40ZT4	400 V	1 Ω	5.4 A	70 W
STP7NK40Z				70 W
STP7NK40ZFP				25 W

Extremely high dv/dt capability

- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitance
- Zener-protected

Applications

Switching applications

Description

lectronics sales office

These high-voltage devices are Zener-protected N-channel Power MOSFETs developed using the SuperMESH[™] technology by STMicroelectronics, an optimization of the well-established PowerMESH[™]. In addition to a significant reduction in on-resistance, these devices are designed to ensure a high level of dv/dt capability for the most demanding applications.

Product status links					
STD7N	STD7NK40ZT4				
STP7	NK40Z				
STP7N	IK40ZFP				
Product	summary				
STD7N	IK40ZT4				
Marking	D7NK40Z				
Package	DPAK				
Packing	Tape and reel				
STP7	NK40Z				
Marking	P7NK40Z				
Package	TO-220				
Packing	Tube				
STP7N	K40ZFP				
Marking	P7NK40ZFP				
Package	TO-220FP				
Packing	Tube				



1 Electrical ratings

Oursels a l	Parameter	Value			
Symbol Parameter -		STD7NK40ZT4	STP7NK40Z	STP7NK40ZFP	Uni
V _{DS}	Drain-source voltage		400		V
V _{DGR}	Drain-gate voltage (R_{GS} = 20 k Ω)		400		V
V_{GS}	Gate-source voltage		±30		V
	Drain current (continuous) at T _C = 25 °C	5.4	5.4	5.4 ⁽¹⁾	A
Ι _D	Drain current (continuous) at T_C = 100 °C	3.4	3.4	3.4 ⁽¹⁾	A
I _{DM} ⁽²⁾	Drain current (pulsed)	21.6	21.6	21.6 ⁽¹⁾	A
P _{TOT}	Total dissipation at T_C = 25 °C	70	70	25	W
I _{AR}	Avalanche current, repetitive or non-repetitive (pulse width is limited by T_J max.)	5.4			A
E _{AS}	Single pulse avalanche energy (starting T _J = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)		130		m
ESD	Gate-source, human body model, $R = 1.5 \text{ k}\Omega, \text{ C} = 100 \text{ pF}$		3		k∖
dv/dt ⁽³⁾	Peak diode recovery voltage slope		4.5		V/n
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink $(t = 1 \text{ s}, T_C = 25 \text{ °C})$			2.5	k∖v
TJ	Operating junction temperature range	-55 to 150		1	°C
T _{stg}	Storage temperature range			-0	

Table 1. Absolute maximum ratings

1. This value is limited by maximum junction temperature.

2. Pulse width is limited by safe operating area.

3. $I_{SD} \leq 5.4 \text{ A}, di/dt \leq 200 \text{ A}/\mu s, V_{DD} < V_{(BR)DSS}$

Table 2. Thermal data

Symbol	Parameter	Value				
Symbol	Falanielei	DPAK	TO-220	TO-220FP	- Unit	
R _{thj-case}	Thermal resistance junction-case	1.78	1.78	5	°C/W	
R _{thj-amb}	Thermal resistance junction-ambient		62.5		°C/W	
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-pcb	50			°C/W	

1. When mounted on an 1-inch² FR-4, 2 Oz copper board.



2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1 mA, V _{GS} = 0 V	400			V
		V_{GS} = 0 V, V_{DS} = 400 V			1	μA
I _{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 400 V, T _C = 125 °C ⁽¹⁾			50	μA
I _{GSS}	Gate body leakage current	V_{GS} = ±20 V, V_{DS} = 0 V			±10	μA
V _{GS(th)}	Gate threshold voltage	V_{DS} = V_{GS} , I_D = 50 μ A	3	3.75	4.5	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 2.7 A		0.85	1	Ω

Table 3. On/off states

1. Defined by design, not subject to production test.

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance			535		
C _{oss}	Output capacitance	V_{DS} = 25 V, f = 1 MHz, V_{GS} = 0 V	-	82	-	pF
C _{rss}	Reverse transfer capacitance			18		
Coss eq. ⁽¹⁾	Equivalent output capacitance	V_{GS} = 0 V, V_{DS} = 0 to 320 V	-	53	-	pF
Qg	Total gate charge	V _{DD} = 320 V, I _D = 5.4 A,		19	26	
Q _{gs}	Gate-source charge	V_{GS} = 0 to 10 V	-	4		nC
Q _{gd}	Gate-drain charge	(see Figure 16. Test circuit for gate charge behavior)		10		

1. C_{oss eq.} is defined as the constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}.

Table 5.	Switching	times
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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = 200 V, I _D = 2.7 A,		15		
t _r	Rise time	R_{G} = 4.7 Ω , V_{GS} = 10 V		15		
t _{d(off)}	Turn-off delay time	(see Figure 15. Test circuit for resistive load switching times and		30	-	
t _f	Fall time	Figure 20. Switching time waveform)		12	-	ns
t _{r(Voff)}	Off-voltage rise time	V _{DD} = 320 V, I _D = 5.4 A,		12		
t _f	Fall time	R_G = 4.7 Ω , V_{GS} = 10 V		10		
t _c	Crossover time	(see Figure 17. Test circuit for inductive load switching and diode recovery times)	-	20	-	

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current				5.4	^
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)	_	-		21.6	A
$V_{SD}^{(2)}$	Forward on voltage	I _{SD} = 5.4 A, V _{GS} = 0 V	-		1.6	V
t _{rr}	Reverse recovery time	I _{SD} = 5.4 A, di/dt = 100 A/μs,		220		ns
Q _{rr}	Reverse recovery charge	V _{DD} = 50 V, T _J = 150 °C		990		nC
I _{RRM}	Reverse recovery current	(see Figure 17. Test circuit for inductive load switching and diode recovery times)	-	9		A

1. Pulsed: pulse duration = $300 \mu s$, duty cycle 1.5%.

2. Pulse width is limited by safe operating area.

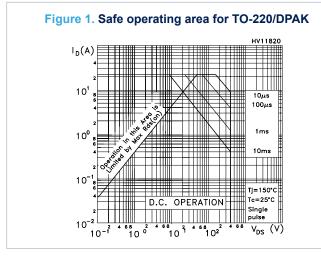
Table 7. Gate-source Zener diode

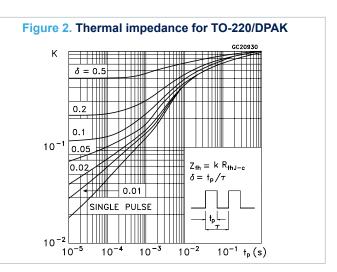
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)GSO}	Gate-source breakdown voltage	I_{GS} = ±1 mA (open drain)	30	-	-	V

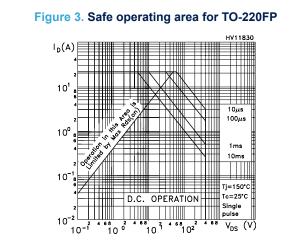
The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.



2.1 Electrical characteristics (curves)







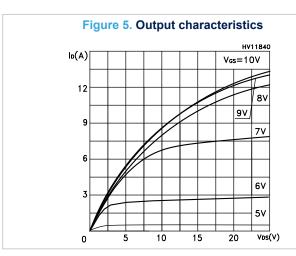
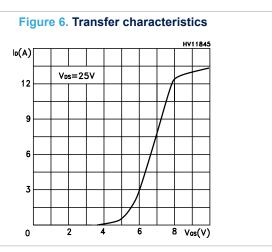
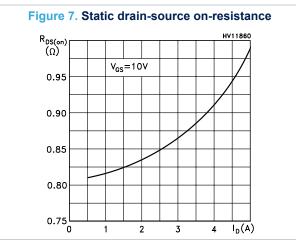
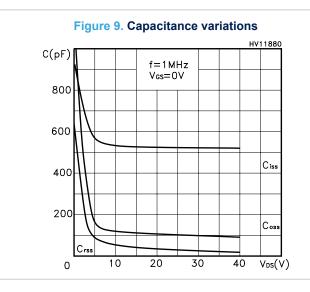


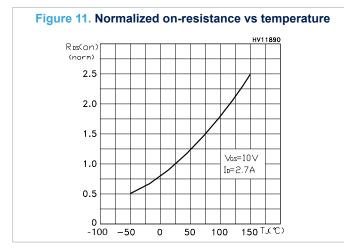
Figure 4. Thermal impedance for TO-220FP Κ GC20940 δ=0. δ=0 δ =0. 10 -1 δ =0.05 δ =0.02 δ =0.01 Single pulse Zth=K*Rthi 10 -2 $\delta = t_p / T$ 10 -3 t _p (s) 10 -4 10 - 3 10 ⁰ 10 -2 10 -1

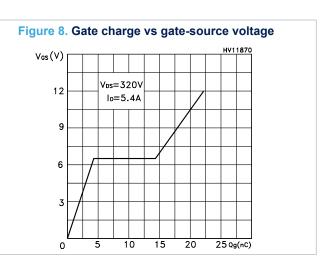












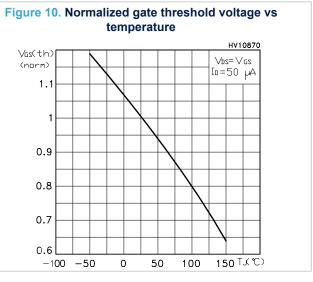
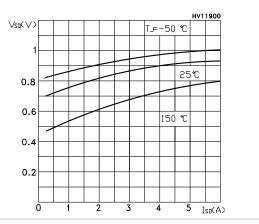
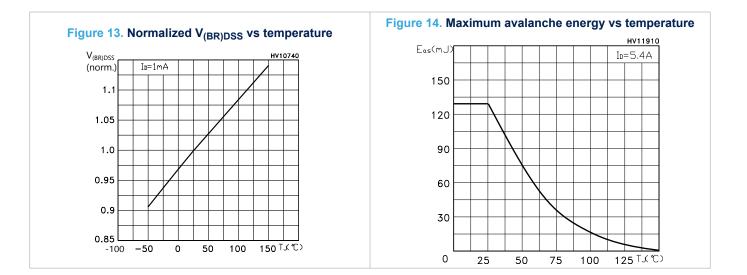


Figure 12. Source-drain diode forward characteristics



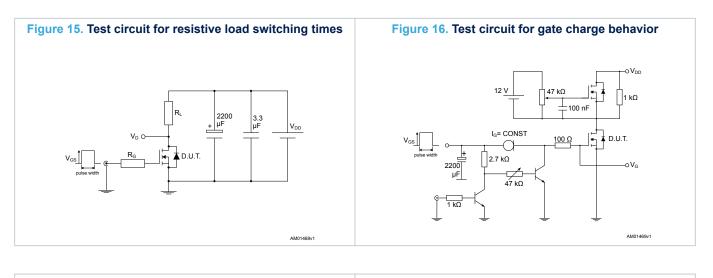


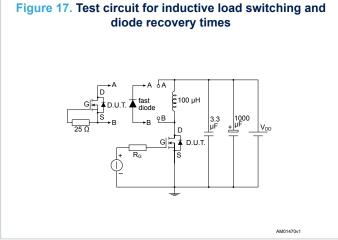


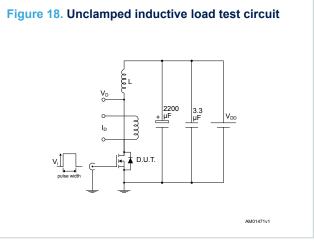


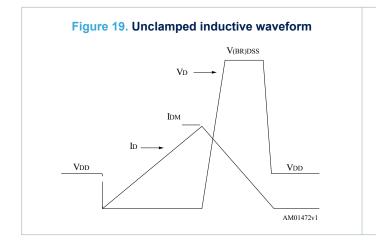


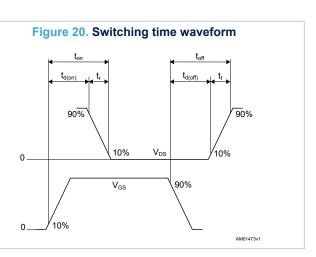
3 Test circuits













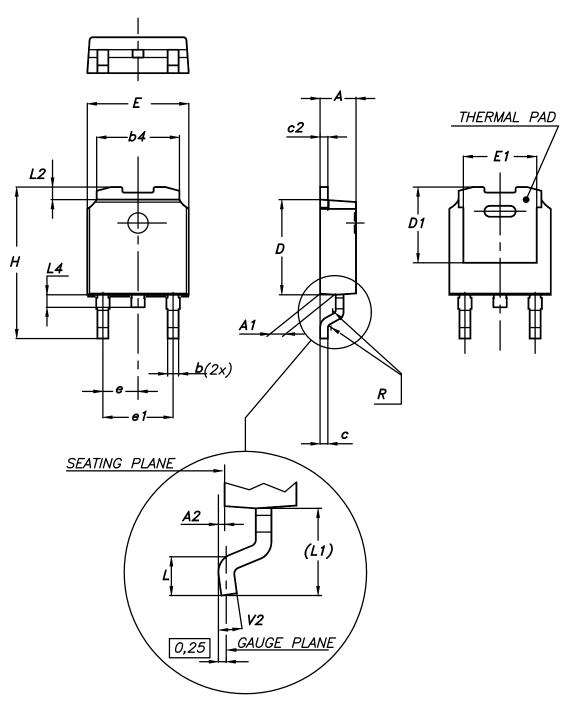
4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.



4.1 DPAK (TO-252) type A package information

Figure 21. DPAK (TO-252) type A package outline



0068772_A_25



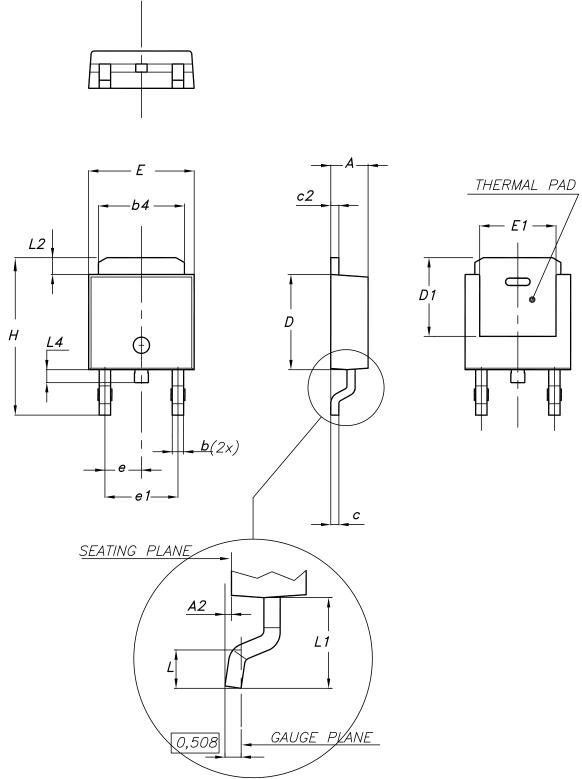
Dim.		mm	
Dim.	Min.	Тур.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
С	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
е	2.159	2.286	2.413
e1	4.445	4.572	4.699
Н	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Table 8. DPAK (TO-252) type A mechanical data



4.2 DPAK (TO-252) type E package information

Figure 22. DPAK (TO-252) type E package outline



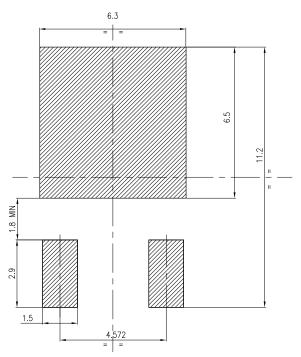
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Dim.		mm		
Dim.	Min.	Тур.	Max.	
A	2.18		2.39	
A2			0.13	
b	0.65		0.884	
b4	4.95		5.46	
С	0.46		0.61	
c2	0.46		0.60	
D	5.97		6.22	
D1	5.21			
E	6.35		6.73	
E1	4.32			
e		2.286		
e1		4.572		
Н	9.94		10.34	
L	1.50		1.78	
L1		2.74		
L2	0.89		1.27	
L4			1.02	

Table 9. DPAK (TO-252) type E mechanical data

Figure 23. DPAK (TO-252) recommended footprint (dimensions are in mm)

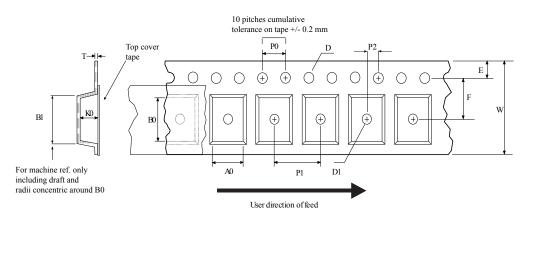


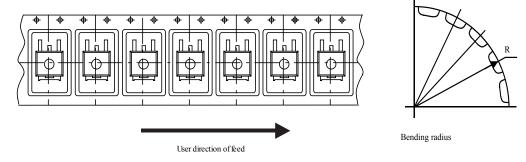
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4.3 DPAK (TO-252) packing information



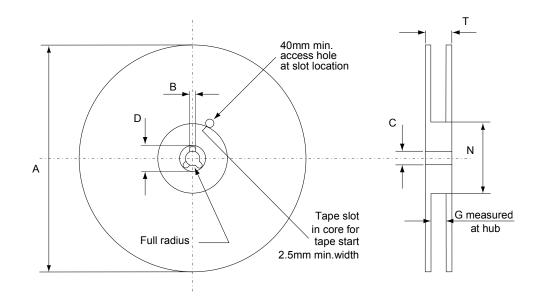




AM08852v1







AM06038v1

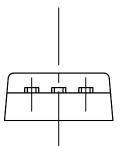
Table 10. DPAK (TO-252) tape and reel mechanical data

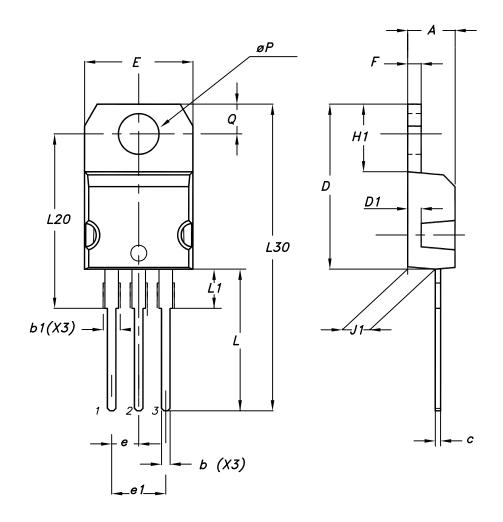
Таре		Reel			
Dim.	mm		Dim	mm	
	Min.	Max.	Dim.	Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	В	1.5	
B1		12.1	С	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	Т		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
Т	0.25	0.35			
W	15.7	16.3			



4.4 TO-220 type A package information

Figure 26. TO-220 type A package outline





0015988_typeA_Rev_21



Dim.	mm			
	Min.	Тур.	Max.	
A	4.40		4.60	
b	0.61		0.88	
b1	1.14		1.55	
С	0.48		0.70	
D	15.25		15.75	
D1		1.27		
E	10.00		10.40	
e	2.40		2.70	
e1	4.95		5.15	
F	1.23		1.32	
H1	6.20		6.60	
J1	2.40		2.72	
L	13.00		14.00	
L1	3.50		3.93	
L20		16.40		
L30		28.90		
øP	3.75		3.85	
Q	2.65		2.95	

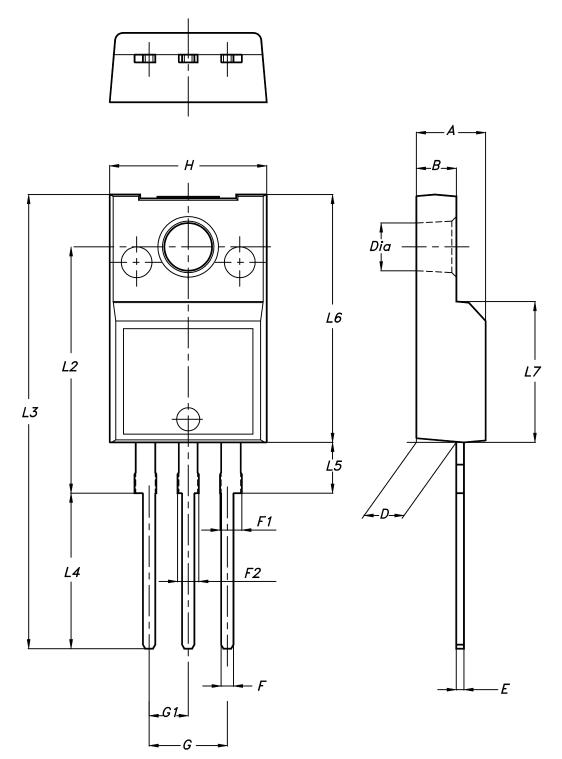
Table 11. TO-220 type A package mechanical data



4.5 TO-220FP package information

57

Figure 27. TO-220FP package outline



7012510_Rev_12_B



Dim.	mm			
Dim.	Min.	Тур.	Max.	
A	4.4		4.6	
В	2.5		2.7	
D	2.5		2.75	
E	0.45		0.7	
F	0.75		1	
F1	1.15		1.70	
F2	1.15		1.70	
G	4.95		5.2	
G1	2.4		2.7	
Н	10		10.4	
L2		16		
L3	28.6		30.6	
L4	9.8		10.6	
L5	2.9		3.6	
L6	15.9		16.4	
L7	9		9.3	
Dia	3		3.2	

Table 12. TO-220FP package mechanical data



Revision history

Table 13. Docun	ent revision history
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Date	Version	Changes
02-Sep-2002	2	Document updated.
11-Jul-2018	3	Part number STD7NK40Z-1 was moved to a separate datasheet, and the document was updated accordingly.
		Updated title, features, applications and description on cover page.
		Updated Section 1 Electrical ratings, Section 2 Electrical characteristics, Section 3 Test circuits and Section 4 Package information.
		Minor text changes



Contents

1	Elect	rical ratings	2		
2	Electrical characteristics				
	2.1	Electrical characteristics (curves)	5		
3	Test o	circuits	8		
4 Package information					
	4.1	DPAK (TO-252) type A package information	9		
	4.2	DPAK (TO-252) type E package information	. 11		
	4.3	DPAK (TO-252) packing information.	. 13		
	4.4	TO-220 type A package information	. 15		
	4.5	TO-220FP package information	. 17		
Revi	ision h	listory	.20		



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